



BOARD LEVEL COOLING - 10-L4LB

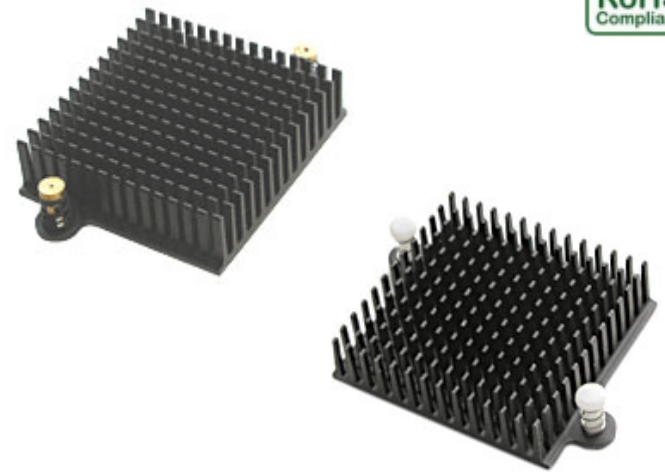
10-L4LB is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. These heat sinks use push pins with springs for mounting. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
10-L4LB-05G	BGA, FPGA
10-L4LB-11G	BGA, FPGA

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Push Pin
Thermal Interface Material	-

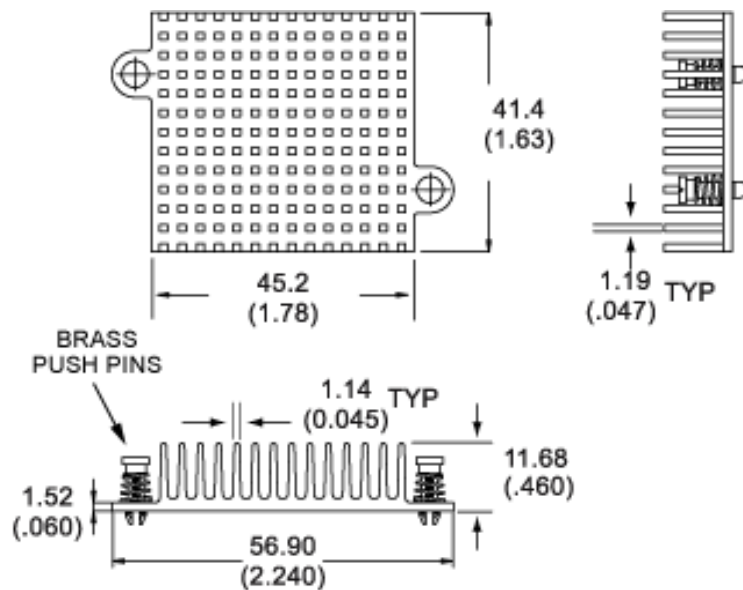


Property	Details
Heat Sink Width (mm)	41.40
Heat Sink Length (mm)	45.20
Heat Sink Height (mm)	11.68
Heat Sink Mounting Direction	Horizontal, Vertical

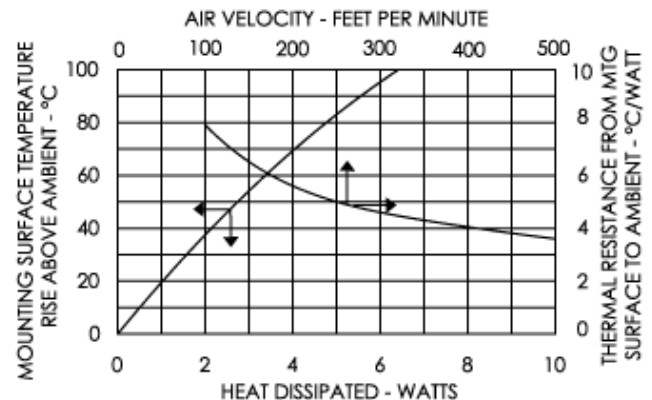
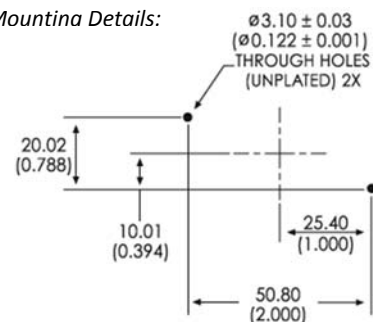
MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

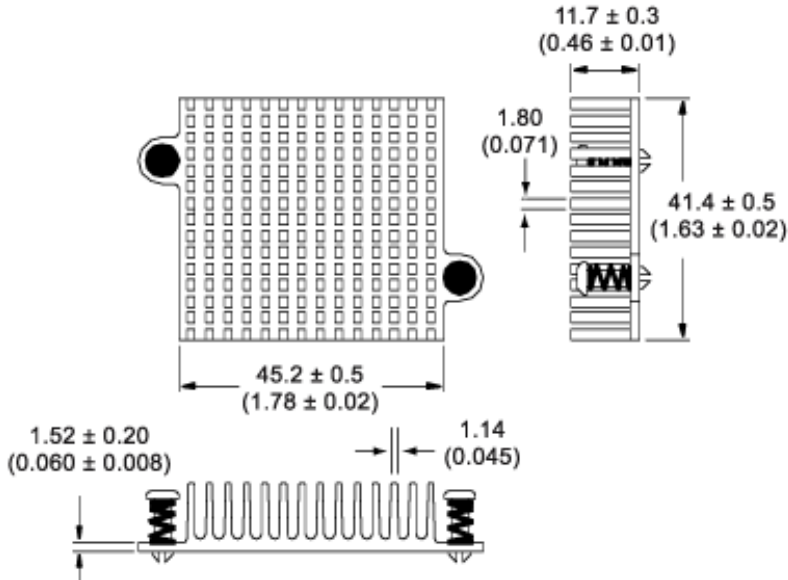
Part Number: 10-L4LB-05G



Mounting Details:



Part Number: 10-L4LB-11G



Mounting Details:

